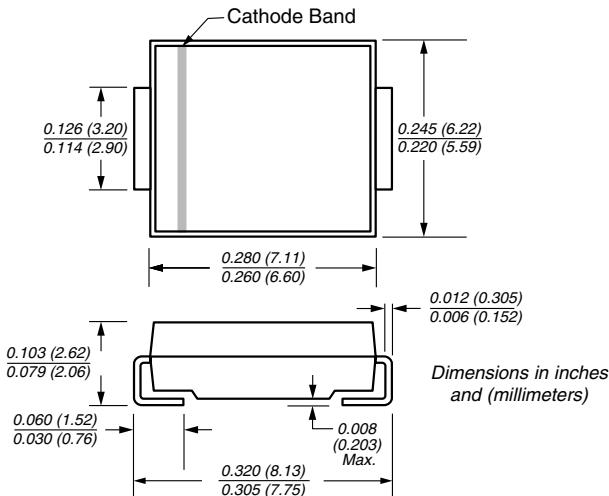
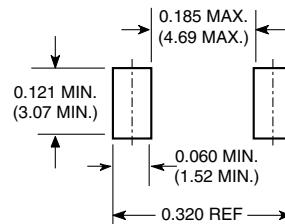



DO-214AB (SMC)

Mounting Pad Layout

Mechanical Data

Case: JEDEC DO-214AB molded plastic body over glass passivated chip

Terminals: Solder plated, solderable per MIL-STD-750, Method 2026

High temperature soldering:
260°C/10 seconds at terminals

Polarity: Color band denotes cathode end

Weight: 0.007 ounce, 0.25 gram

Features

- Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- For surface mount applications
- Low profile package
- Built-in strain relief, ideal for automated placement
- Glass passivated chip junction

Maximum Ratings & Thermal Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Parameter	Symbol	S3A	S3B	S3D	S3G	S3J	S3K	S3M	Unit
Device marking code		SA	SB	SD	SG	SJ	SK	SM	
Maximum recurrent peak reverse voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current at T _L =103°C ⁽¹⁾	I _{F(AV)}	3.0						A	
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method) T _L =75°C	I _{FSM}	100						A	
Typical thermal resistance ⁽¹⁾	R _{θJA} R _{θJL}	47 13						°C/W	
Operating junction and storage temperature range	T _J , T _{STG}	-55 to +150						°C	

Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Maximum instantaneous forward voltage at 2.5A	V _F	1.15	V
Maximum DC reverse current TA=25°C at rated DC blocking voltage TA=125°C	I _R	10 250	µA
Typical reverse recovery time at I _F =0.5A, I _R =1.0A, I _{rr} =0.25A	t _{rr}	2.5	µs
Typical junction capacitance at 4.0V, 1MHz	C _J	60	pF

Note: (1) Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.3 x 0.3" (8.0 x 8.0mm) copper pad areas

Surface Mount Glass Passivated Rectifier

Ratings and

Characteristic Curves ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig. 1 - Forward Current Derating Curve

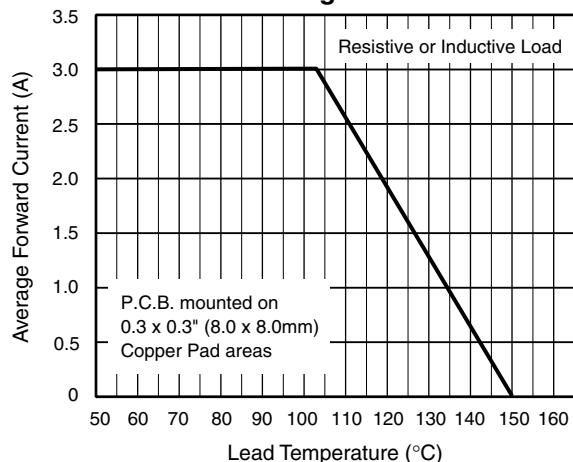


Fig. 2 - Maximum Non-Repetitive Peak Forward Surge Current

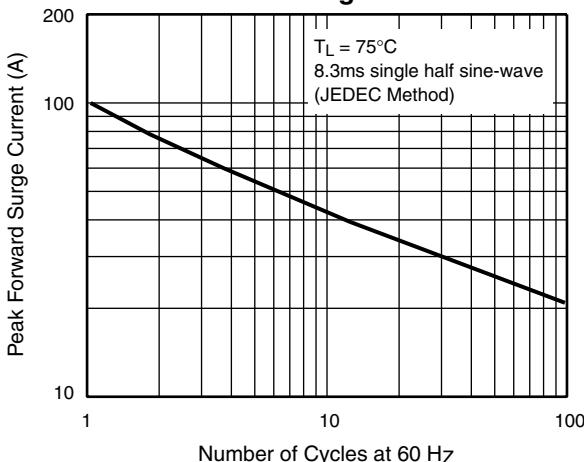


Fig. 3 - Typical Instantaneous Forward Characteristics

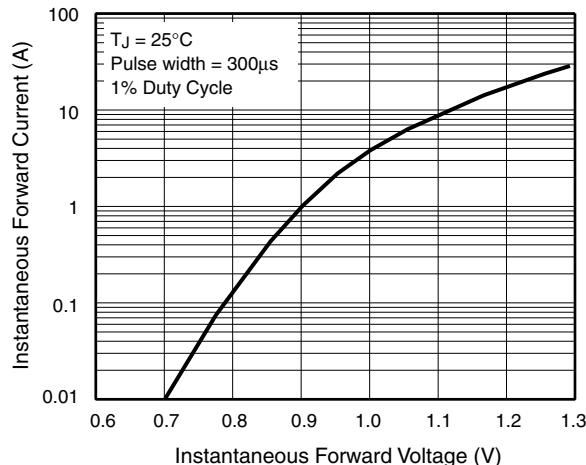


Fig. 4 - Typical Reverse Characteristics

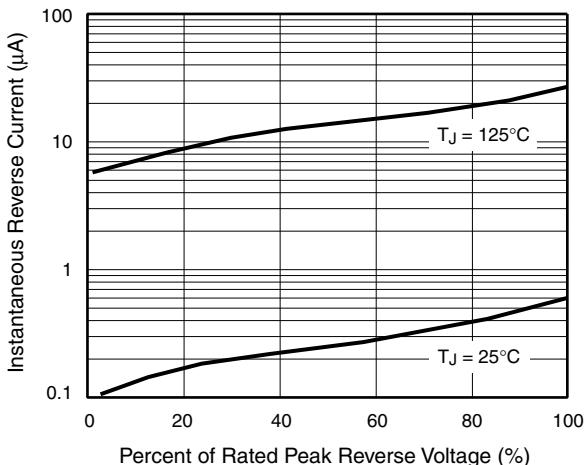


Fig. 5 - Typical Junction Capacitance

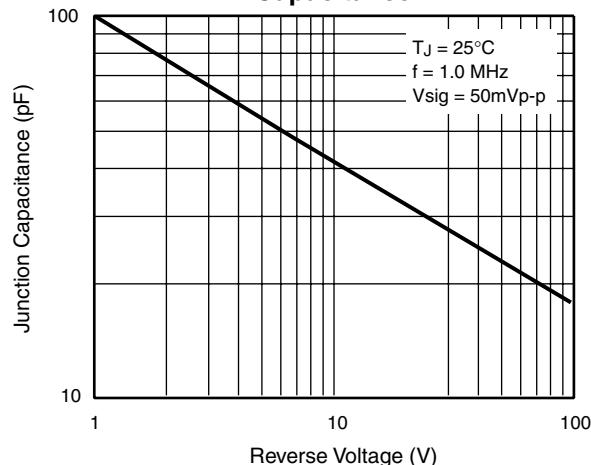


Fig. 6 - Typical Transient Thermal Impedance

